

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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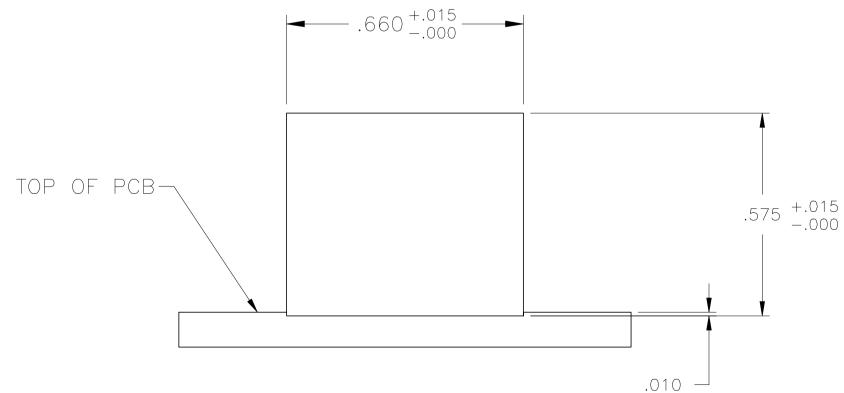
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Suggested Panel Cutout

REVISIONS F | EC-1411035 COMPANY LOGO CHANGE 14JAN2015 TL KZ

MATERIALS:

HOUSING - THERMOPLASTIC PA46 TE250F6 POLYESTER FLAMMABILITY RATING UL 94V-0.

SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30µINCH SEMI-BRIGHT

NICKEL. SOLDER TABS POST DIPPED WITH 100 µINCH MIN SAC SOLDER.

MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50µINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50µINCH MIN HARD GOLD FINISH PLATE SOLDERTAILS WITH 100µINCH MIN MATTE TIN AND/OR SAC SOLDER

LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" x .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80 μ INCH SILVER OVER 40 μ INCH NICKEL UNDERPLATE OVER 40 μ INCH COPPER UNDERPLATE. POST-PLATED WITH 100 µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

3 MAGNETICS

-APPLICATION: 10/100/1000 BASE-T

-IMPEDANCE: 100 OHMS

-TURNS RATIO (CHIP:CABLE): 1:1 ALL FOUR PAIRS

-OPEN CIRCUIT INDUCTANCE (OCL): 350µH MIN @100kHz, 0.1VRMS,

8madc bias from 0 $^{\circ}$ to 70 $^{\circ}$, all four pairs

-ALL FOUR PAIRS BI-DIRECTIONAL

-PERFORMANCE @ 25℃:

INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz

RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz

12-20LOG(f/80)dB MIN FROM 40.1MHz TO 100MHz

CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz

33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz

COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz - ISOLATION VOLTAGE: 2250 VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500 V/SEC.

4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.

LEDS WITHOUT BUILT-IN RESISTOR

LEDS ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20 mA

LED COLOR: DOMINANT WAVELENGTH (λ D): GREEN 568 nm TYP @ IF=20 mA

FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20 mA

DOMINANT WAVELENGTH (λ D): YELLOW 588 nm TYP @ IF=20 mA

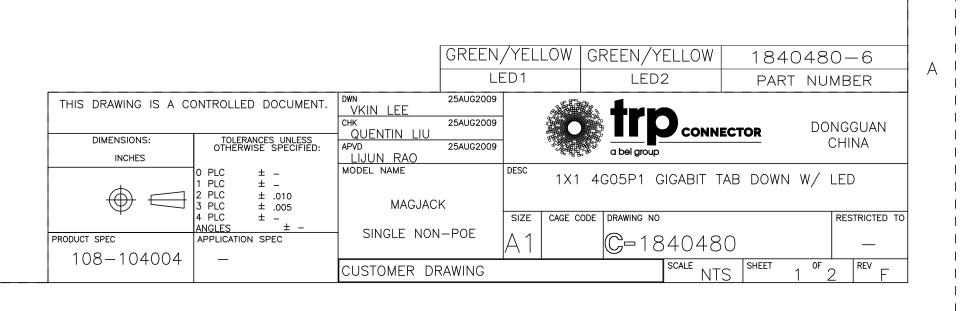
FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF-20 mA

INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL TO SUPPORT AUTO-MDI/MDIX.

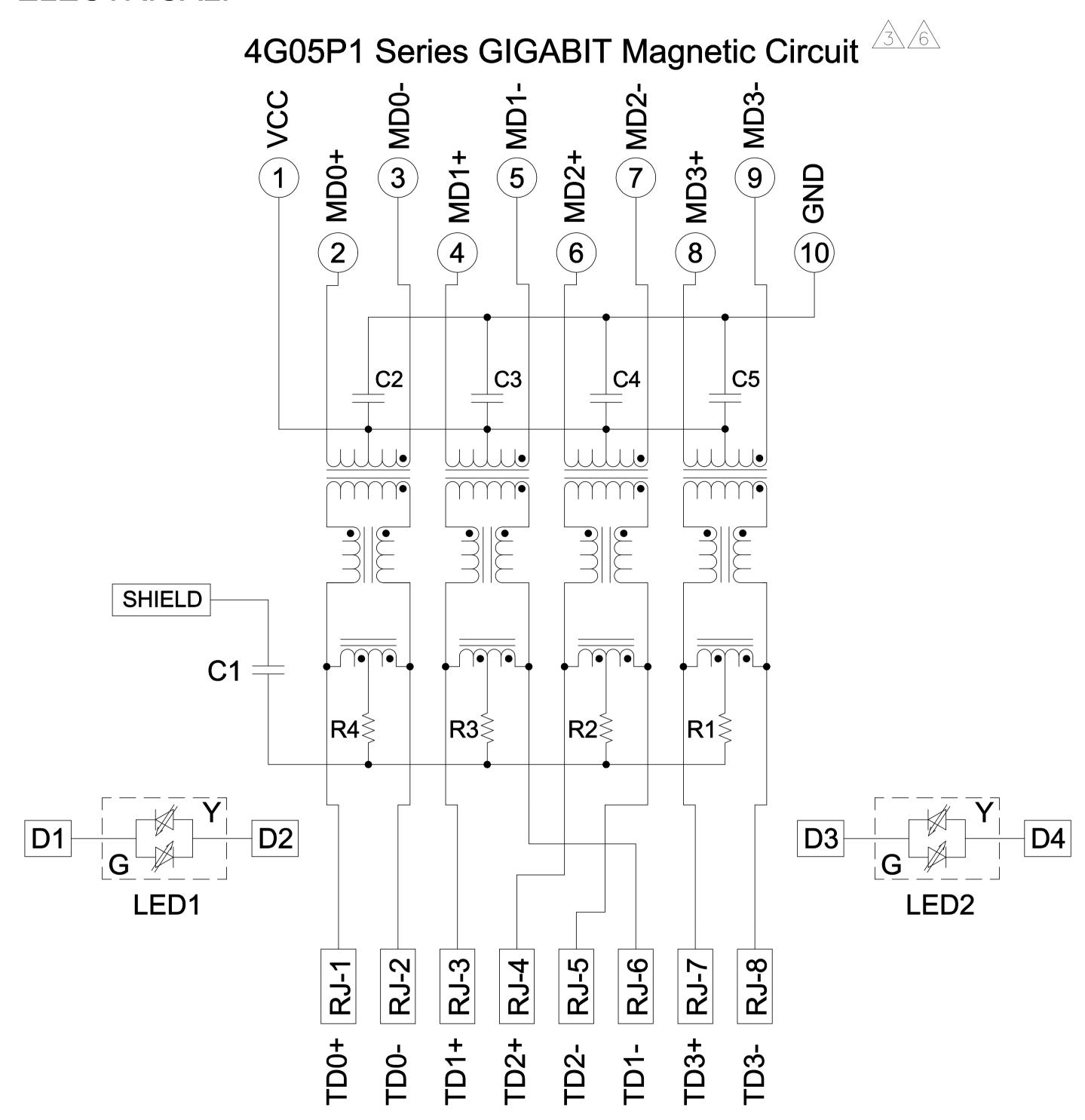
 $\stackrel{ o}{ o}$ trp connector logo, part number, date code, country of origin and agency approval marking in APPROXIMATE LOCATION SHOWN.

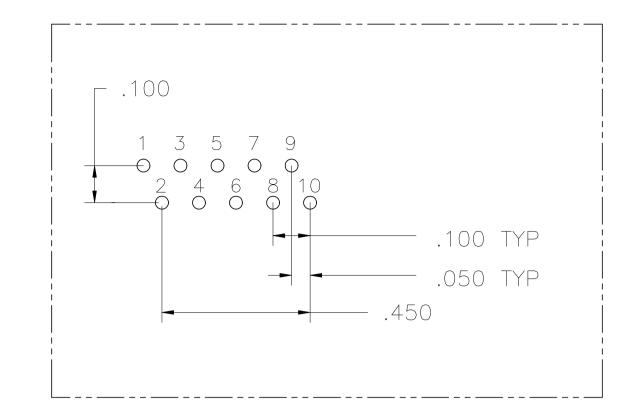
8. THE PART IS COMPLIANT TO BOTH WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 150°C ABOVE, 120 SECONDS TO 180 SECONDS, PEAK SOLDERING TEMPERATURE IS 265 °C MAX, 10 SECONDS MAX; AND IR REFLOW SOLDERING PROESS, PEAK SOLDERING TEMPERATURE 260°C MAX DURATION TIME 10 SECONDS MAX, OVER 230 °C WITHIN 40 SECONDS TO 60 SECONDS.

LED LENS ARE RECESSED TO SHIELD SURFACE

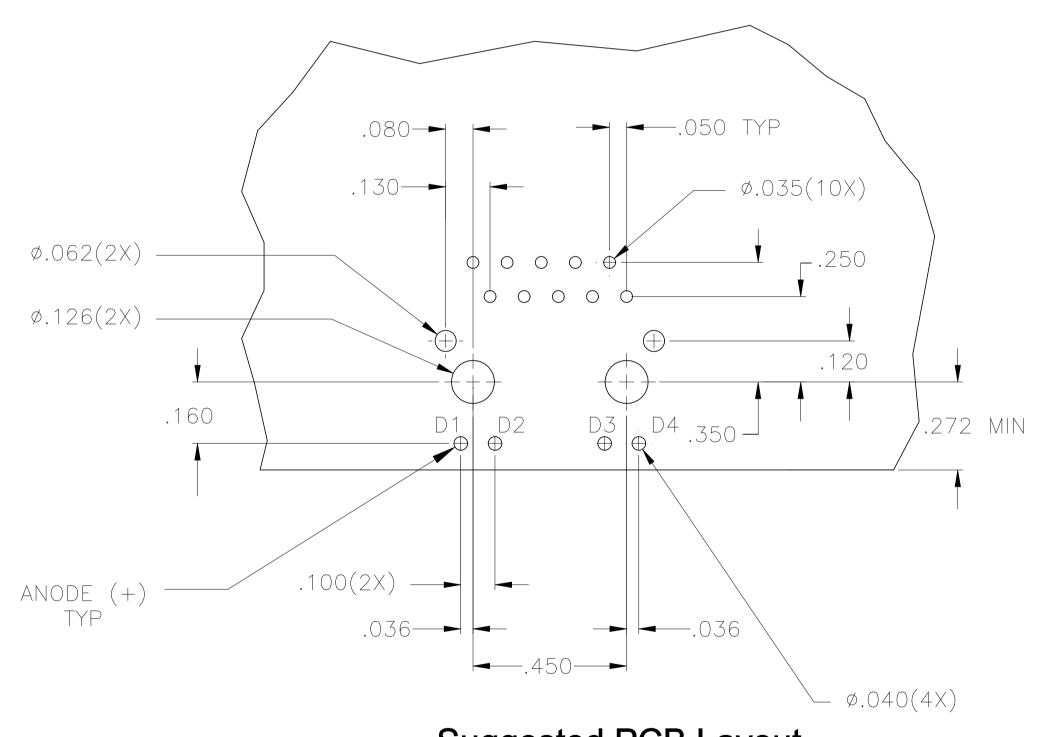


ELECTRICAL:





Pin Designations



Suggested PCB Layout (Component Side)

C1 =1000 pF, 2kV CAPACITOR

R1-R4 = 75 OHMS, 1/16 W RESISTORS

C2-C5 = 0.1uF, 50V, X7R CAPACITORS

